

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

- 1-8. (canceled)
9. (original) A method for forming ball grid array packages, comprising:
- providing a substrate;
- engaging a stencil with a first surface of the substrate, the stencil comprising:
- a center region having a first set of generally circular holes formed therein;
- and
- a first outer region disposed radially outwardly from the center region and having a second set of generally circular holes formed therein, wherein the diameter of each of the generally circular holes of the second set is greater than the diameter of each of the generally circular holes of the first set;
- depositing solder paste over the stencil;
- removing the stencil, thereby creating a plurality of solder paste regions on the substrate; and
- coupling a plurality of solder balls to respective ones of the solder paste regions.
10. (original) The method of Claim 9, wherein the diameter of each of the generally circular holes of the second set is approximately ten to twenty percent greater than the diameter of each of the generally circular holes of the first set.
11. (original) The method of Claim 9, wherein the stencil comprises a second outer region disposed radially outwardly from the first outer region and

having a third set of generally circular holes formed therein, wherein the diameter of each of generally circular holes of the third set is greater than the diameter of each of the generally circular holes of the second set.

12. (original) The method of Claim 11, wherein the diameter of each of the generally circular holes of the third set is approximately five to ten percent greater than the diameter of each of the generally circular holes of the second set.

13. (original) The method of Claim 9, further comprising providing the stencil with generally square shape.

14. (original) The method of Claim 13, further comprising:
providing the center region with a generally square shape;
providing the first outer region with a generally square shape; and
orienting the first outer region approximately 45 degrees with respect to the center region.

15. (original) The method of Claim 9, further comprising aligning the first and second set of generally circular holes in rows and columns, wherein a pitch between adjacent generally circular holes is between approximately 0.5 millimeter and 0.9 millimeter.

16-20. (canceled)

21. (new) A method for forming a pattern of solder paste on a warped substrate, comprising the steps of:

engaging a stencil with the substrate, the stencil having a pattern of holes of various diameters;

depositing solder paste over the stencil on the substrate such that the amount of solder paste deposited at various locations on the substrate is a function of the extent of the warp of the substrate.

22. (new) The method of claim 21, further comprising a step of incorporating a solder ball to each solder paste deposited areas.

23. (new) The method of claim 22, in which the step of incorporating further generating a ball grid array device complying with a predetermined coplanarity tolerance.